

规格书编号 : HDBF14005B21SP01

SPEC NO : HDBF14005B21SP01

产品规格书

SPECIFICATION

CUSTOMER 客 户: _____

PRODUCT 产 品: _____ SAW FILTER _____

MODEL NO 型 号: _____ HDBF14005B21 SMD-21 _____

PREPARED 编 制: 汤康君 CHECKED 审 核: 邓 攀

APPROVED 批 准: 汤康君 D A T E 日 期: 2010-7-9

客户确认 CUSTOMER RECEIVED:

审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司
Shoulder Electronics Limited

[illegible]

1. SCOPE

This specification shall cover the characteristics of SAW filter with HDBF14005B21 used for the page system.

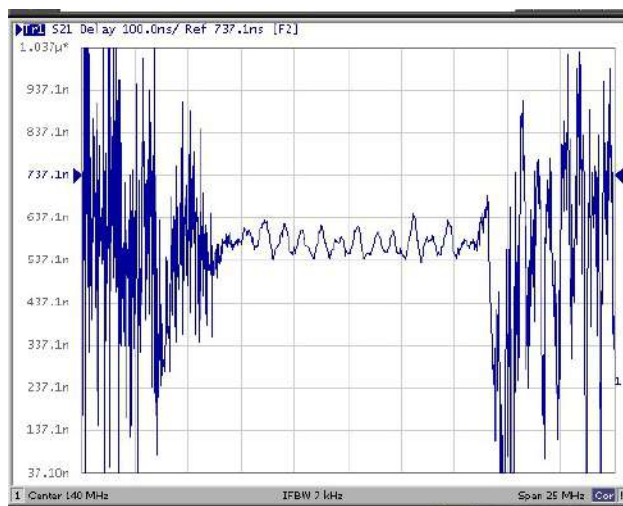
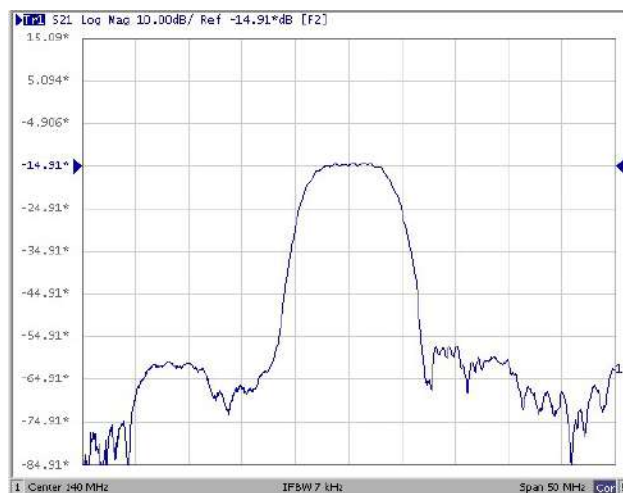
2. ELECTRICAL SPECIFICATION

Maximum Input Power	+10dBm
DC voltage	10V
Storage Temperature Range	-45℃ to +85℃
Operation Temperature Range	-40℃ to +85℃

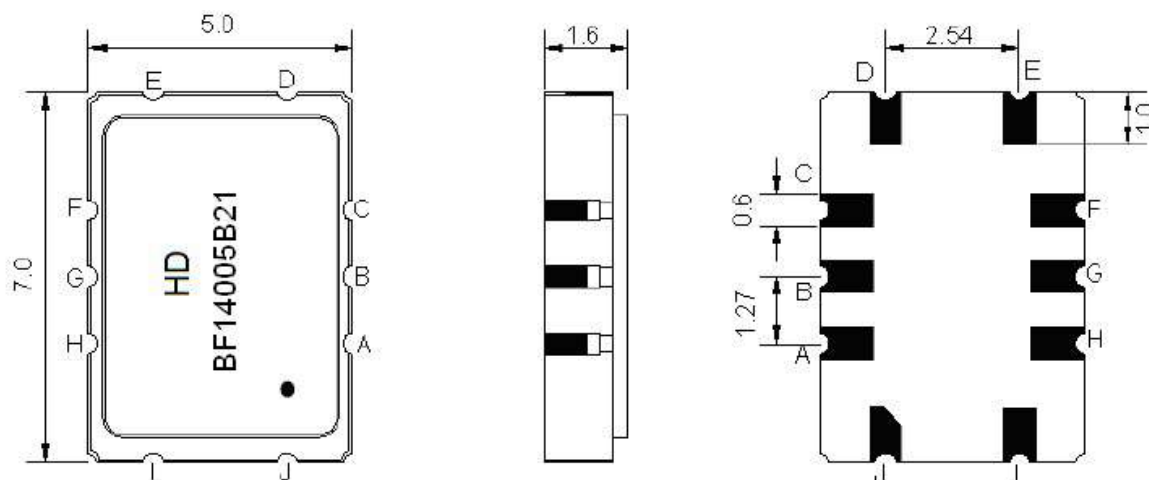
2.2 Electronic Characteristics

Parameter	Min.	Typical.	Max.	Unit
Center Frequency	139.7	140	140.3	MHz
Insertion loss		15	18	dB
Passband ripple(-1 dB)		0.8	1	dB
-1dB Bandwidth	5	5.6		MHz
-3dB Bandwidth	6.5	7		MHz
Rejection:	38	40		dB
Absolute Delay		0.55	0.7	usec
Group Delay Variation		0.1	0.12	usec
Temperature Coefficient		-87		ppm/℃
Package Size	SMD-21			

3. Typical Frequency Response



4.DIMENSION



- ① HD : Brand
- ② BF11535A21 : Model Name
- Index Dot

Pin Description	
A,B,C,F,G,H	Ground
I	Input
J	Ground
D	Output
E	Ground

5. ENVIRONMENTAL CHARACTERISTICS

5-1 High temperature exposure

Subject the device to +85℃ for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2.2.

5-2 Low temperature exposure

Subject the device to -40℃ for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2.2.

5-3 Temperature cycling

Subject the device to a low temperature of -40℃ for 30 minutes. Following by a high temperature of +85℃ for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in 2.2.

5-4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at 260℃ ±10℃ for 10±1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in 2.2.

5-5 Solderability

Subject the device terminals into the solder bath at $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in 2.2.

5-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in 2.2.

5-7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in 2.2.

6. REMARK

6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.